

denomination	SB 155	SB 160	SB 180	VP 160	VP 180	WP 180
characteristics	SB 155	SB 160	SB 180	VP 160	VP 180	WP 180
thermal class	158°C	174°C	195°C	174°C	195°C	195°C
base coat	mod. Polyurethane	mod. Polyurethane	mod. Polyurethane	mod. Polyurethane	mod. Polyurethane	Polyesterimide
bonding coat	Polyvinylbutyral	Polyvinylbutyral	Polyvinylbutyral	Polyamide	Polyamide	Polyamide
reference to the international Standards	IEC 60317-35, IEC 60317-2 MW 131	IEC 60317-35, IEC 60317-2 MW 131	IEC 60317-35, IEC 60317-2 MW 131	IEC 60317-35, IEC 60317-21 MW 131	IEC 60317-35, IEC 60317-21 MW 131	IEC 60317-36, IEC 60317-22
UL - approval	file E 143017	file E 143017	file E 143017	file E 143017	file E 143017	file E 143017
diameters range (mm)	0,010 0,045mm	0,010-0,045mm	0,010-0,045mm	0,010-0,045mm	0,010-0,045mm	0,010-0,045mm
cut through temperature IEC 60851-6.4 Ø 0,040 mm	210°C	245°C	260°C	245°C	260°C	360°C
heat shock IEC 60851-6.3 Ø 0,040 mm	>180°C	>180°C	>200°C	>180°C	>200°C	>200°C
significant properties	hot-air-, oven-, resistance- and solvent bonding			hot-air and solvent bonding		hot-air bonding
applications	coils for medical technology: hearing aids, pacemakers, motor for dentist drills etc. coils for entertainment industry: audioheads, microphones, headphones, mobile phones, coils for watches, clockworks, movements etc. coils for measuring instruments, control instruments, transponders, coils for cards: credit cards, telephone cards, hotel cards, identification cards, etc					
storage property	storage cool, dry and light protected. Humidity <50%, stable temperature < 23°C					
	≤6 months	≤6 months	≤6 months	≤3 months	≤3 months	≤3 months
recommended bonding temperature	140°C	140°C	140°C	170 - 200°C	170 - 210°C	180 - 220°C
resoftening temperature IEC 60851-3 7.1.2.4	≥ 120°C	≥ 120°C	≥ 120°C	≥ 150°C	≥ 150°C	≥ 180°C
breakdown voltage at 20 °C, 35% humidit. Ø 0.04mm: ISODRA values	160 V/μm	160 V/μm	160 V/μm	160 V/μm	160 V/μm	160 V/μm
Elongation for Grade 1 wire. Ø 0.04mm: acc. IEC 60851-3.3	≥ 9%	≥ 9%	≥ 9%	≥ 9%	≥ 9%	≥ 9%
ISODRA values	≥ 18%	≥ 18%	≥ 18%	≥ 18%	≥ 18%	≥ 18%
solderability for Grade 1. Ø 0.04mm: acc. IEC 60851.4.5	1.0s / 375°C	1.0s / 375°C	1.0s / 390°C	2.0s / 390°C	2.0s / 390°C	2.0s / 470°C
ISODRA values	<1.0s / 375°C	<1.0s / 375°C	<1.0s / 390°C	<2.0s / 390°C	<2.0s / 390°C	<2.0s / 470°C